

Method and Apparatus for Wafer Scale Testing

ABSTRACT OF THE DISCLOSURE

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- Methods and apparatus are provided for I/O pads of unsingulated integrated circuits, to be connected to electrical equipment. A translator plate is interposed between a wafer and tester. The translator plate includes a substrate having two major opposing surfaces, each surface having terminals disposed thereon, and
- 10 electrical pathways disposed through the substrate to provide for electrical continuity between at least one terminal on a first surface and at least one terminal on the second surface. The translator plate, when interposed between wafer and tester, makes electrical contact with one or more I/O pads of a plurality of integrated circuits on the wafer, providing an electrical pathway therethrough. An anisotropic
 - 15 conductor is disposed between the wafer and the translator plate. A vibratory mechanism, oriented to provide substantially horizontal vibratory motion to the wafer, may be coupled to the wafer to assist disposing the translator plate and anisotropic conductor over the wafer.